

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Todd O. Bolken

Serial No.: 10/791,192

Filed: March 2, 2004

For: TWO-STAGE TRANSFER MOLDING
DEVICE TO ENCAPSULATE MMC
MODULE

Confirmation No.: 1966

Examiner: D. Zarneke

Group Art Unit: 2891

Attorney Docket No.: 2269-4794.4US
(01-0185.04/US)

Notice of Allowance Mailed:

May 1, 2007

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July 25, 2007

**FEE ADDRESSEE FOR RECEIPT OF PTO NOTICES
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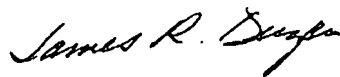
1. This letter is to specify that the FEE ADDRESSEE for this patent is:

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2. The Customer Number for the Fee Addressee is **26809**.
3. Any prior FEE ADDRESSEE for this patent is hereby revoked.
4. It is certified that the person whose signature appears below has the authority to change the FEE ADDRESSEE for this patent.

Respectfully submitted,



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Date: July 25, 2007

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